

IPW60R160P6-VB Datasheet

N-Channel 600V (D-S) Super Junction Power MOSFET

| PRODUCT SUMMA | RY | |
|--|------------------------|-------|
| V _{DS} (V) at T _J max. | 600 |) |
| R _{DS(on)} at 25 °C (Ω) | V _{GS} = 10 V | 0.160 |

FEATURES

- Low figure-of-merit (FOM) Ron x Qg
- Low input capacitance (Ciss)
- Reduced switching and conduction losses
- Ultra low gate charge (Q_a)
- Avalanche energy rated (UIS)

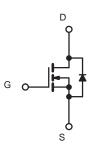
APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- - High-intensity discharge (HID)
 - Fluorescent ballast lighting



TO-247





N-Channel MOSFET

| ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted) | | | | | | | |
|--|-------------------------|---|-----------------------------------|-------------|------|--|--|
| PARAMETER | | | SYMBOL | LIMIT | UNIT | | |
| Drain-Source Voltage | | | V_{DS} | 600 | V | | |
| Gate-Source Voltage | | | V_{GS} | ± 30 | V | | |
| Continuous Drain Current (T _J = 150 °C) | \/ at 10 \/ | $T_C = 25 ^{\circ}C$ $T_C = 100 ^{\circ}C$ | - I _D | 20 | | | |
| | V _{GS} at 10 V | T _C = 100 °C | | 12 | Α | | |
| Pulsed Drain Current ^a | | | I _{DM} | 60 | | | |
| Linear Derating Factor | | | | 1.67 | W/°C | | |
| Single Pulse Avalanche Energy b | | | E _{AS} | 1000 | mJ | | |
| Maximum Power Dissipation | | | P_{D} | 160 | W | | |
| Operating Junction and Storage Temperature Range | | | T _J , T _{stg} | -55 to +150 | °C | | |
| Drain-Source Voltage Slope | T _J = 125 °C | | dV/dt | 50 | V/ns | | |
| Reverse Diode dV/dt ^d | | αν/ατ | 15 | V/IIS | | | |
| Soldering Recommendations (Peak Temperature) c | for | 10 s | | 260 | °C | | |

- a. Repetitive rating; pulse width limited by maximum junction temperature. b. $V_{DD}=100$ V, starting $T_{J}=25$ °C, L = 30mH, $R_{g}=25$ Ω , $I_{AS}=13A$.
- c. 1.6 mm from case.
- d. $I_{SD} \le I_D$, dI/dt = 100 A/ μ s, starting $T_J = 25$ °C.



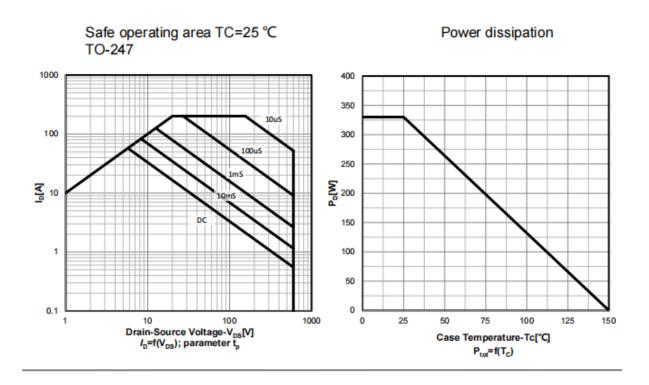
| THERMAL RESISTANCE RATI | NGS | | | |
|----------------------------------|-------------------|------|------|-------|
| PARAMETER | SYMBOL | TYP. | MAX. | UNIT |
| Maximum Junction-to-Ambient | R _{thJA} | - | 62 | °C/W |
| Maximum Junction-to-Case (Drain) | R _{thJC} | - | 0.38 | G/ VV |

| PARAMETER | SYMBOL | TEST CONDITIONS | | MIN. | TYP. | MAX. | UNIT |
|---|-----------------------|---|---|------|-------|-------|------|
| Static | | - | | | | | • |
| Drain-Source Breakdown Voltage | V_{DS} | V _{GS} : | = 0 V, I _D = 1 mA | 600 | - | - | V |
| V _{DS} Temperature Coefficient | $\Delta V_{DS}/T_{J}$ | Reference | e to 25 °C, I _D = 1 mA | - | 0.70 | - | V/°C |
| Gate-Source Threshold Voltage (N) | V _{GS(th)} | V _{DS} = | = V _{GS} , I _D = 250 μA | 2.5 | - | 4.5 | V |
| | | | V _{GS} = ± 20 V | - | - | ± 100 | nA |
| Gate-Source Leakage | I_{GSS} | | V _{GS} = ± 30 V | - | - | ± 1 | μA |
| | | | = 600V, V _{GS} = 0 V | - | - | 1 | μA |
| Zero Gate Voltage Drain Current | I _{DSS} | | /, V _{GS} = 0 V, T _J = 125 °C | - | - | 100 | |
| Drain-Source On-State Resistance | R _{DS(on)} | V _{GS} = 10 V | | - | 0.160 | - | Ω |
| Forward Transconductance | 9 _{fs} | V _{DS} = 30 V, I _D = 7A | | 1 | 5.6 | - | S |
| Dynamic | | - | | | ' | | |
| Input Capacitance | C _{iss} | $V_{GS} = 0 \text{ V},$ $V_{DS} = 100 \text{ V},$ $f = 1 \text{ MHz}$ | | - | 2300 | - | pF |
| Output Capacitance | Coss | | | - | 330 | - | |
| Reverse Transfer Capacitance | C _{rss} | | | - | 4 | - | |
| Effective Output Capacitance, Energy Related ^a | C _{o(er)} | - V _{DS} = 0 V to 520 V, V _{GS} = 0 V | | - | 63 | - | |
| Effective Output Capacitance, Time Related ^b | C _{o(tr)} | | | - | 213 | - | |
| Total Gate Charge | Qg | | | - | 62 | - | |
| Gate-Source Charge | Q _{gs} | V _{GS} = 10 V | $I_D = 20 \text{ A}, V_{DS} = 520 \text{ V}$ | - | 39 | - | nC |
| Gate-Drain Charge | Q _{gd} | | | - | 4 7 | - | |
| Turn-On Delay Time | t _{d(on)} | | | 1 | 18 | 25 | |
| Rise Time | t _r | $V_{DD} = 520 \text{ V}, I_D = 20A,$ | | ı | 24 | 55 | ns |
| Turn-Off Delay Time | t _{d(off)} | | | - | 8 0 | - | 113 |
| Fall Time | t _f | $V_{GS} = 10 \text{ V}, R_g = 9.1 \Omega$ | | - | 1 2 | - | |
| Gate Input Resistance | R_g | f = 1 MHz, open drain | | ı | 0.8 | - | Ω |
| Drain-Source Body Diode Characteristic | s | | | | | | |
| Continuous Source-Drain Diode Current | I _S | MOSFET symbol showing the integral reverse p - n junction diode | | - | - | 20 | ^ |
| Pulsed Diode Forward Current | I _{SM} | | | - | - | 60 | - A |
| Diode Forward Voltage | V _{SD} | T _J = 25 °C, I _S = 8 A, V _{GS} = 0 V | | - | - | 1.5 | V |
| Reverse Recovery Time | t _{rr} | | | - | 520 | - | ns |
| Reverse Recovery Charge | Q _{rr} | T _J = 25 °C, $I_F = I_S = 8 \text{ A}$, $dI/dt = 100 \text{ A/}\mu\text{s}$, $V_R = 400 \text{ V}$ | | - | 5.8 | - | μC |
| Reverse Recovery Current | I _{RRM} | | | | 4 5 | | A |

Notes

- a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} . b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .





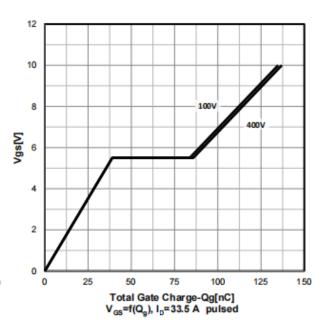
Typ. output characteristics T_i =25 $^{\circ}$ C Transfer characteristics 300 300 25°C . I_D, Drain Current [A] Drain Current [A] 200 150°C -0 5 10 0 15 20 0 2 10 12 V_{GS}, Gate-Source Voltage [V] V_{DS}, Drain to Source Voltage [V]



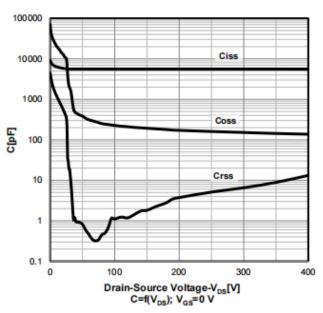
Typ. drain-source on-state resistance

80
70
60
60
40
30
20
0 15 30 45 60 75 90
Drain-Source Current-I_D[A]
R_{DS}(on)=f(I_D); parameter:V_{GS}

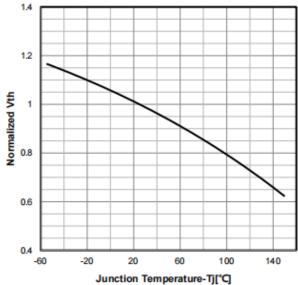
Typ. gate charge characteristics



Typ. capacitances



Normalized $V_{\text{GS(th)}}$ characteristics

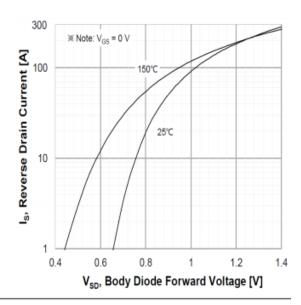




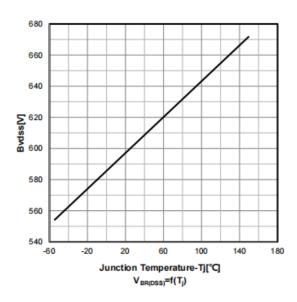
On-resistance vs temperature

120 100 80 60 40 40 20 Junction Temperature-TJ[°C] R_{DS}(on)=f(T_J); I_D=33.5 A; V_{GS}=10 V

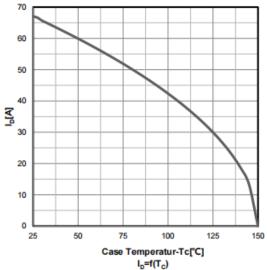
Forward characteristics of reverse diode



Drain-source breakdown voltage



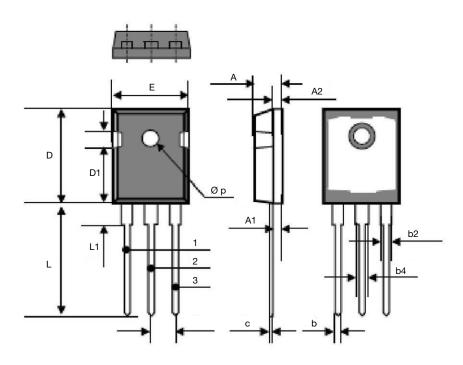
Drain current vs temperature



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TO-247



| DIM. | MILLIN | METERS | INCHES | | |
|------|--------|--------|-----------|-------|--|
| | MIN. | MAX. | MIN. | MAX. | |
| А | 4.70 | 5.31 | 0.185 | 0.209 | |
| A1 | 2.21 | 2.59 | 0.087 | 0.102 | |
| A2 | 1.50 | 2.49 | 0.059 | 0.098 | |
| b | 0.99 | 1.40 | 0.039 | 0.055 | |
| b2 | 1.65 | 2.41 | 0.065 | 0.095 | |
| b4 | 2.59 | 3.43 | 0.102 | 0.135 | |
| С | 0.61 | BSC | 0.024 BSC | | |
| D | 20.80 | 21.46 | 0.819 | 0.845 | |
| D1 | 3.68 | 5.49 | 0.145 | 0.216 | |
| (e) | 5.46 | BSC | 0.215 | BSC | |
| E | 15.49 | 16.26 | 0.610 | 0.640 | |
| L | 19.81 | 20.32 | 0.780 | 0.800 | |
| L1 | 4.06 | 4.50 | 0.160 | 0.177 | |
| Øр | 3.51 | 3.66 | 0.138 | 0.144 | |



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STF5N65M6 IRF40H233XTMA1 STU5N65M6 DMN6022SSD-13 DMN13M9UCA6-7 DMTH10H4M6SPS-13 DMN2990UFB-7B
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